

ABSTRACT

5 A polishing-head system capable of precisely controlling a polishing rate for a substrate, such as a wafer, and more particularly a polishing rate at an edge portion is disclosed. The polishing-head system includes a polishing head, a head shaft, a head rotating mechanism, a multi-path rotary joint, a fluid supply line, and a pressure regulator, wherein the polishing head has a substrate pressing surface, a retainer ring, and pressure
10 chambers arranged along a circumferential direction of the retainer ring, the head shaft has shaft flow-passages communicating with the pressure chambers, respectively, and the multi-path rotary joint is configured to sequentially provide a communication between the fluid supply line and the shaft flow-passages each time the head shaft makes one revolution.

15

FIG. 2